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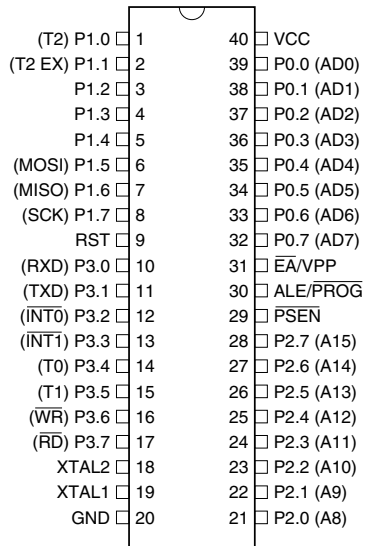
Applications of "[Embedded - Microcontrollers](#)"

Details

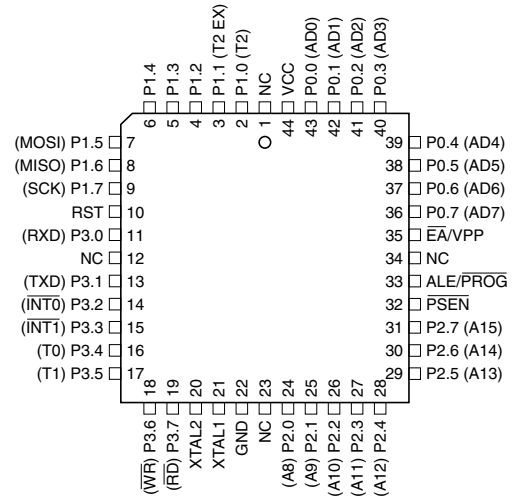
Product Status	Active
Core Processor	8051
Core Size	8-Bit
Speed	24MHz
Connectivity	UART/USART
Peripherals	WDT
Number of I/O	32
Program Memory Size	8KB (8K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	256 x 8
Voltage - Supply (Vcc/Vdd)	4V ~ 5.5V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-TQFP
Supplier Device Package	44-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/at89s52-24au

2. Pin Configurations

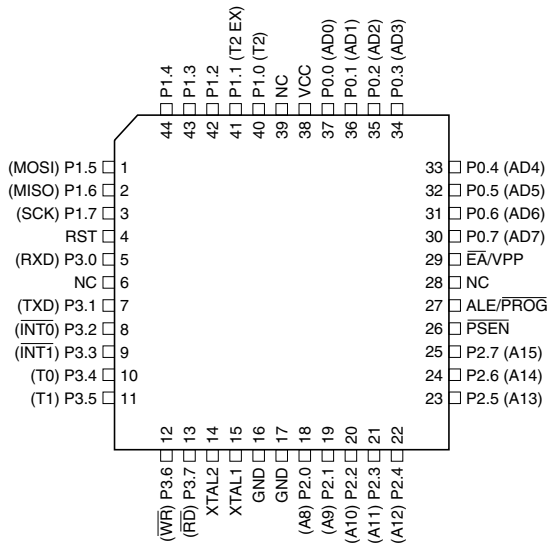
2.1 40-lead PDIP



2.3 44-lead PLCC



2.2 44-lead TQFP



4.9 $\overline{\text{PSEN}}$

Program Store Enable ($\overline{\text{PSEN}}$) is the read strobe to external program memory.

When the AT89S52 is executing code from external program memory, $\overline{\text{PSEN}}$ is activated twice each machine cycle, except that two $\overline{\text{PSEN}}$ activations are skipped during each access to external data memory.

4.10 $\overline{\text{EA/VPP}}$

External Access Enable. $\overline{\text{EA}}$ must be strapped to GND in order to enable the device to fetch code from external program memory locations starting at 0000H up to FFFFH. Note, however, that if lock bit 1 is programmed, $\overline{\text{EA}}$ will be internally latched on reset.

$\overline{\text{EA}}$ should be strapped to V_{CC} for internal program executions.

This pin also receives the 12-volt programming enable voltage (V_{PP}) during Flash programming.

4.11 XTAL1

Input to the inverting oscillator amplifier and input to the internal clock operating circuit.

4.12 XTAL2

Output from the inverting oscillator amplifier.

5. Special Function Registers

A map of the on-chip memory area called the Special Function Register (SFR) space is shown in Table 5-1.

Note that not all of the addresses are occupied, and unoccupied addresses may not be implemented on the chip. Read accesses to these addresses will in general return random data, and write accesses will have an indeterminate effect.

User software should not write 1s to these unlisted locations, since they may be used in future products to invoke new features. In that case, the reset or inactive values of the new bits will always be 0.

Timer 2 Registers: Control and status bits are contained in registers T2CON (shown in Table 5-2) and T2MOD (shown in Table 10-2) for Timer 2. The register pair (RCAP2H, RCAP2L) are the Capture/Reload registers for Timer 2 in 16-bit capture mode or 16-bit auto-reload mode.

Interrupt Registers: The individual interrupt enable bits are in the IE register. Two priorities can be set for each of the six interrupt sources in the IP register.

Table 5-1. AT89S52 SFR Map and Reset Values

0F8H								0FFH
0F0H	B 00000000							0F7H
0E8H								0EFH
0E0H	ACC 00000000							0E7H
0D8H								0DFH
0D0H	PSW 00000000							0D7H
0C8H	T2CON 00000000	T2MOD XXXXXX00	RCAP2L 00000000	RCAP2H 00000000	TL2 00000000	TH2 00000000		0CFH
0C0H								0C7H
0B8H	IP XX000000							0BFH
0B0H	P3 11111111							0B7H
0A8H	IE 0X000000							0AFH
0A0H	P2 11111111		AUXR1 XXXXXXX0				WDRST XXXXXXXX	0A7H
98H	SCON 00000000	SBUF XXXXXXXX						9FH
90H	P1 11111111							97H
88H	TCON 00000000	TMOD 00000000	TL0 00000000	TL1 00000000	TH0 00000000	TH1 00000000	AUXR XXX00XX0	8FH
80H	P0 11111111	SP 00000111	DP0L 00000000	DP0H 00000000	DP1L 00000000	DP1H 00000000		PCON 0XXX0000 87H

Table 5-2. T2CON – Timer/Counter 2 Control Register

T2CON Address = 0C8H

Reset Value = 0000 0000B

Bit Addressable

Bit	TF2	EXF2	RCLK	TCLK	EXEN2	TR2	C/ $\overline{T2}$	CP/ $\overline{RL2}$
	7	6	5	4	3	2	1	0

Symbol	Function
TF2	Timer 2 overflow flag set by a Timer 2 overflow and must be cleared by software. TF2 will not be set when either RCLK = 1 or TCLK = 1.
EXF2	Timer 2 external flag set when either a capture or reload is caused by a negative transition on T2EX and EXEN2 = 1. When Timer 2 interrupt is enabled, EXF2 = 1 will cause the CPU to vector to the Timer 2 interrupt routine. EXF2 must be cleared by software. EXF2 does not cause an interrupt in up/down counter mode (DCEN = 1).
RCLK	Receive clock enable. When set, causes the serial port to use Timer 2 overflow pulses for its receive clock in serial port Modes 1 and 3. RCLK = 0 causes Timer 1 overflow to be used for the receive clock.
TCLK	Transmit clock enable. When set, causes the serial port to use Timer 2 overflow pulses for its transmit clock in serial port Modes 1 and 3. TCLK = 0 causes Timer 1 overflows to be used for the transmit clock.
EXEN2	Timer 2 external enable. When set, allows a capture or reload to occur as a result of a negative transition on T2EX if Timer 2 is not being used to clock the serial port. EXEN2 = 0 causes Timer 2 to ignore events at T2EX.
TR2	Start/Stop control for Timer 2. TR2 = 1 starts the timer.
C/ $\overline{T2}$	Timer or counter select for Timer 2. C/ $\overline{T2}$ = 0 for timer function. C/ $\overline{T2}$ = 1 for external event counter (falling edge triggered).
CP/ $\overline{RL2}$	Capture/Reload select. CP/ $\overline{RL2}$ = 1 causes captures to occur on negative transitions at T2EX if EXEN2 = 1. CP/ $\overline{RL2}$ = 0 causes automatic reloads to occur when Timer 2 overflows or negative transitions occur at T2EX when EXEN2 = 1. When either RCLK or TCLK = 1, this bit is ignored and the timer is forced to auto-reload on Timer 2 overflow.

Table 5-3. AUXR: Auxiliary Register

AUXR

Address = 8EH

Reset Value = XXX00XX0B

Not Bit Addressable

	—	—	—	WDIDLE	DISRTO	—	—	DISALE
Bit	7	6	5	4	3	2	1	0

—

Reserved for future expansion

DISALE

Disable/Enable ALE

DISALE

Operating Mode

0

ALE is emitted at a constant rate of 1/6 the oscillator frequency

1

ALE is active only during a MOVX or MOVC instruction

DISRTO

Disable/Enable Reset out

DISRTO

0

Reset pin is driven High after WDT times out

1

Reset pin is input only

WDIDLE

Disable/Enable WDT in IDLE mode

WDIDLE

0

WDT continues to count in IDLE mode

1

WDT halts counting in IDLE mode

Dual Data Pointer Registers: To facilitate accessing both internal and external data memory, two banks of 16-bit Data Pointer Registers are provided: DP0 at SFR address locations 82H-83H and DP1 at 84H-85H. Bit DPS = 0 in SFR AUXR1 selects DP0 and DPS = 1 selects DP1. The user should **ALWAYS** initialize the DPS bit to the appropriate value before accessing the respective Data Pointer Register.

Power Off Flag: The Power Off Flag (POF) is located at bit 4 (PCON.4) in the PCON SFR. POF is set to “1” during power up. It can be set and rest under software control and is not affected by reset.

Table 5-4. AUXR1: Auxiliary Register 1

AUXR1

Address = A2H

Reset Value = XXXXXXX0B

Not Bit Addressable

	—	—	—	—	—	—	—	DPS
Bit	7	6	5	4	3	2	1	0

—

Reserved for future expansion

DPS

Data Pointer Register Select

DPS

0

Selects DPTR Registers DP0L, DP0H

1

Selects DPTR Registers DP1L, DP1H

6. Memory Organization

MCS-51 devices have a separate address space for Program and Data Memory. Up to 64K bytes each of external Program and Data Memory can be addressed.

6.1 Program Memory

If the \overline{EA} pin is connected to GND, all program fetches are directed to external memory.

On the AT89S52, if \overline{EA} is connected to V_{CC} , program fetches to addresses 0000H through 1FFFH are directed to internal memory and fetches to addresses 2000H through FFFFH are to external memory.

6.2 Data Memory

The AT89S52 implements 256 bytes of on-chip RAM. The upper 128 bytes occupy a parallel address space to the Special Function Registers. This means that the upper 128 bytes have the same addresses as the SFR space but are physically separate from SFR space.

When an instruction accesses an internal location above address 7FH, the address mode used in the instruction specifies whether the CPU accesses the upper 128 bytes of RAM or the SFR space. Instructions which use direct addressing access the SFR space.

For example, the following direct addressing instruction accesses the SFR at location 0A0H (which is P2).

```
MOV 0A0H, #data
```

Instructions that use indirect addressing access the upper 128 bytes of RAM. For example, the following indirect addressing instruction, where R0 contains 0A0H, accesses the data byte at address 0A0H, rather than P2 (whose address is 0A0H).

```
MOV @R0, #data
```

Note that stack operations are examples of indirect addressing, so the upper 128 bytes of data RAM are available as stack space.

7. Watchdog Timer (One-time Enabled with Reset-out)

The WDT is intended as a recovery method in situations where the CPU may be subjected to software upsets. The WDT consists of a 14-bit counter and the Watchdog Timer Reset (WDTRST) SFR. The WDT is defaulted to disable from exiting reset. To enable the WDT, a user must write 01EH and 0E1H in sequence to the WDTRST register (SFR location 0A6H). When the WDT is enabled, it will increment every machine cycle while the oscillator is running. The WDT timeout period is dependent on the external clock frequency. There is no way to disable the WDT except through reset (either hardware reset or WDT overflow reset). When WDT overflows, it will drive an output RESET HIGH pulse at the RST pin.

7.1 Using the WDT

To enable the WDT, a user must write 01EH and 0E1H in sequence to the WDTRST register (SFR location 0A6H). When the WDT is enabled, the user needs to service it by writing 01EH and 0E1H to WDTRST to avoid a WDT overflow. The 14-bit counter overflows when it reaches 16383 (3FFFH), and this will reset the device. When the WDT is enabled, it will increment every machine cycle while the oscillator is running. This means the user must reset the WDT at least every 16383 machine cycles. To reset the WDT the user must write 01EH and 0E1H to WDTRST. WDTRST is a write-only register. The WDT counter cannot be read or written. When

Figure 10-1. Timer in Capture Mode

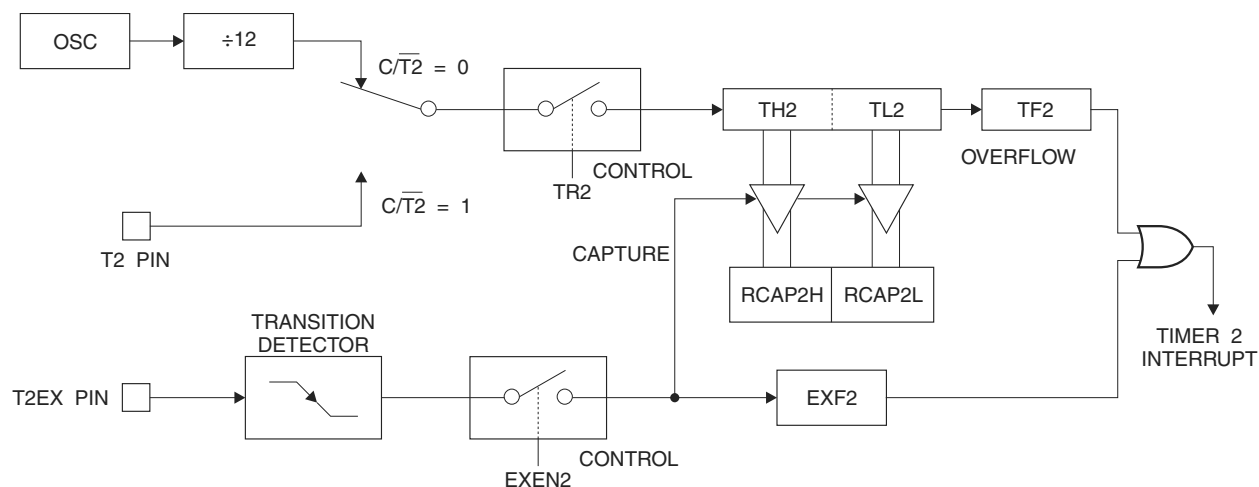


Table 10-2. T2MOD – Timer 2 Mode Control Register

T2MOD Address = 0C9H						Reset Value = XXXX XX00B		
Not Bit Addressable								
Bit	–	–	–	–	–	–	T2OE	DCEN
	7	6	5	4	3	2	1	0

Symbol	Function
–	Not implemented, reserved for future
T2OE	Timer 2 Output Enable bit
DCEN	When set, this bit allows Timer 2 to be configured as an up/down counter

Figure 10-2 shows Timer 2 automatically counting up when DCEN = 0. In this mode, two options are selected by bit EXEN2 in T2CON. If EXEN2 = 0, Timer 2 counts up to 0FFFFH and then sets the TF2 bit upon overflow. The overflow also causes the timer registers to be reloaded with the 16-bit value in RCAP2H and RCAP2L. The values in Timer in Capture Mode RCAP2H and RCAP2L are preset by software. If EXEN2 = 1, a 16-bit reload can be triggered either by an overflow or by a 1-to-0 transition at external input T2EX. This transition also sets the EXF2 bit. Both the TF2 and EXF2 bits can generate an interrupt if enabled.

Setting the DCEN bit enables Timer 2 to count up or down, as shown in Figure 10-2. In this mode, the T2EX pin controls the direction of the count. A logic 1 at T2EX makes Timer 2 count up. The timer will overflow at 0FFFFH and set the TF2 bit. This overflow also causes the 16-bit value in RCAP2H and RCAP2L to be reloaded into the timer registers, TH2 and TL2, respectively.

A logic 0 at T2EX makes Timer 2 count down. The timer underflows when TH2 and TL2 equal the values stored in RCAP2H and RCAP2L. The underflow sets the TF2 bit and causes 0FFFFH to be reloaded into the timer registers.

The EXF2 bit toggles whenever Timer 2 overflows or underflows and can be used as a 17th bit of resolution. In this operating mode, EXF2 does not flag an interrupt.

Figure 10-2. Timer 2 Auto Reload Mode (DCEN = 0)

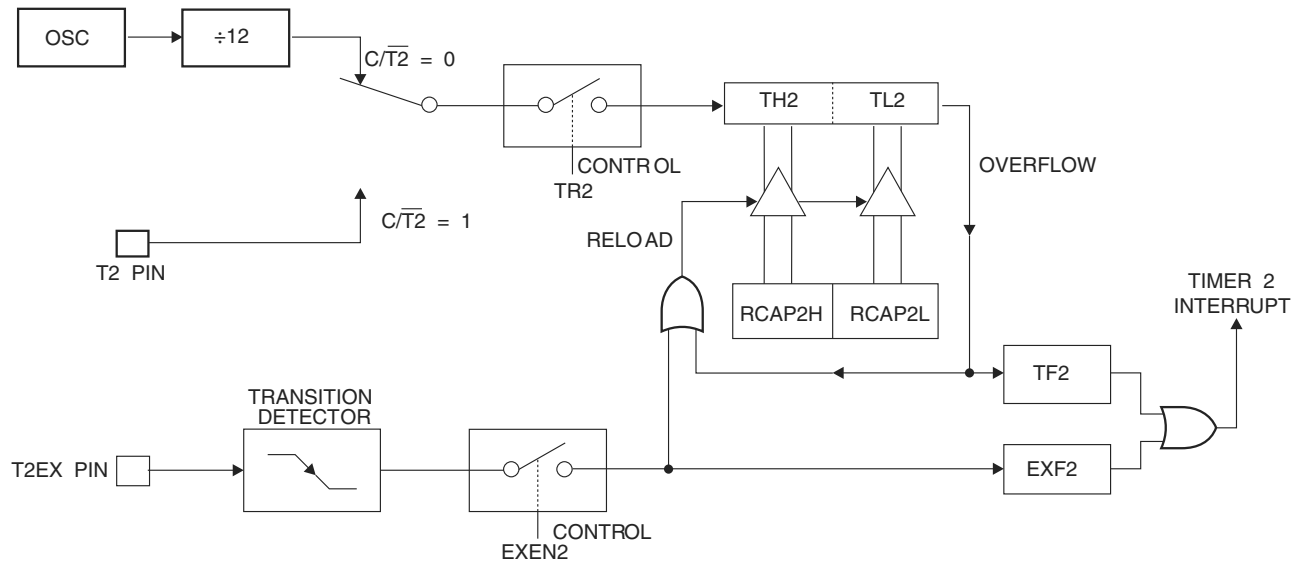
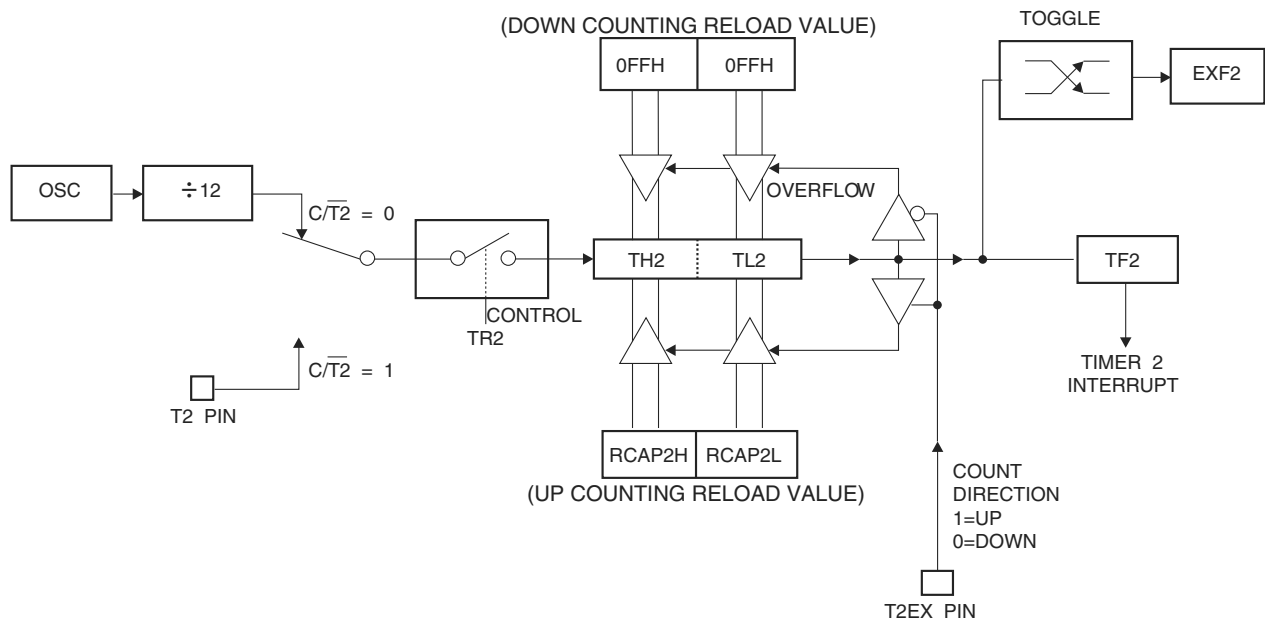


Figure 10-3. Timer 2 Auto Reload Mode (DCEN = 1)



14. Oscillator Characteristics

XTAL1 and XTAL2 are the input and output, respectively, of an inverting amplifier that can be configured for use as an on-chip oscillator, as shown in Figure 16-1. Either a quartz crystal or ceramic resonator may be used. To drive the device from an external clock source, XTAL2 should be left unconnected while XTAL1 is driven, as shown in Figure 16-2. There are no requirements on the duty cycle of the external clock signal, since the input to the internal clocking circuitry is through a divide-by-two flip-flop, but minimum and maximum voltage high and low time specifications must be observed.

15. Idle Mode

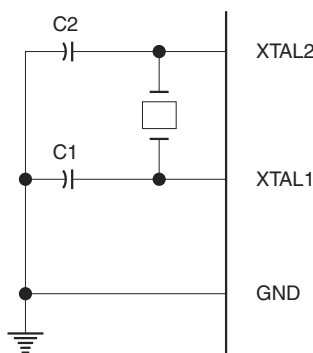
In idle mode, the CPU puts itself to sleep while all the on-chip peripherals remain active. The mode is invoked by software. The content of the on-chip RAM and all the special functions registers remain unchanged during this mode. The idle mode can be terminated by any enabled interrupt or by a hardware reset.

Note that when idle mode is terminated by a hardware reset, the device normally resumes program execution from where it left off, up to two machine cycles before the internal reset algorithm takes control. On-chip hardware inhibits access to internal RAM in this event, but access to the port pins is not inhibited. To eliminate the possibility of an unexpected write to a port pin when idle mode is terminated by a reset, the instruction following the one that invokes idle mode should not write to a port pin or to external memory.

16. Power-down Mode

In the Power-down mode, the oscillator is stopped, and the instruction that invokes Power-down is the last instruction executed. The on-chip RAM and Special Function Registers retain their values until the Power-down mode is terminated. Exit from Power-down mode can be initiated either by a hardware reset or by an enabled external interrupt. Reset redefines the SFRs but does not change the on-chip RAM. The reset should not be activated before V_{CC} is restored to its normal operating level and must be held active long enough to allow the oscillator to restart and stabilize.

Figure 16-1. Oscillator Connections



Note: 1. $C1, C2 = 30 \text{ pF} \pm 10 \text{ pF}$ for Crystals
 $= 40 \text{ pF} \pm 10 \text{ pF}$ for Ceramic Resonators

Figure 16-2. External Clock Drive Configuration

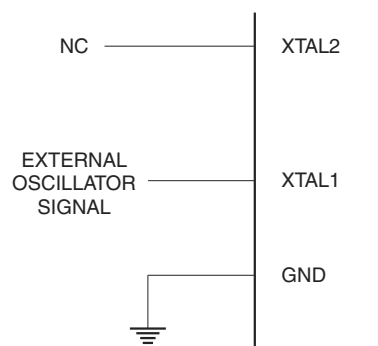


Table 16-1. Status of External Pins During Idle and Power-down Modes

Mode	Program Memory	ALE	$\overline{\text{PSEN}}$	PORT0	PORT1	PORT2	PORT3
Idle	Internal	1	1	Data	Data	Data	Data
Idle	External	1	1	Float	Data	Address	Data
Power-down	Internal	0	0	Data	Data	Data	Data
Power-down	External	0	0	Float	Data	Data	Data

17. Program Memory Lock Bits

The AT89S52 has three lock bits that can be left unprogrammed (U) or can be programmed (P) to obtain the additional features listed in Table 17-1.

Table 17-1. Lock Bit Protection Modes

Program Lock Bits				Protection Type
	LB1	LB2	LB3	
1	U	U	U	No program lock features
2	P	U	U	MOVC instructions executed from external program memory are disabled from fetching code bytes from internal memory, $\overline{\text{EA}}$ is sampled and latched on reset, and further programming of the Flash memory is disabled
3	P	P	U	Same as mode 2, but verify is also disabled
4	P	P	P	Same as mode 3, but external execution is also disabled

When lock bit 1 is programmed, the logic level at the $\overline{\text{EA}}$ pin is sampled and latched during reset. If the device is powered up without a reset, the latch initializes to a random value and holds that value until reset is activated. The latched value of $\overline{\text{EA}}$ must agree with the current logic level at that pin in order for the device to function properly.

19. Programming the Flash – Serial Mode

The Code memory array can be programmed using the serial ISP interface while RST is pulled to V_{CC} . The serial interface consists of pins SCK, MOSI (input) and MISO (output). After RST is set high, the Programming Enable instruction needs to be executed first before other operations can be executed. Before a reprogramming sequence can occur, a Chip Erase operation is required.

The Chip Erase operation turns the content of every memory location in the Code array into FFH.

Either an external system clock can be supplied at pin XTAL1 or a crystal needs to be connected across pins XTAL1 and XTAL2. The maximum serial clock (SCK) frequency should be less than 1/16 of the crystal frequency. With a 33 MHz oscillator clock, the maximum SCK frequency is 2 MHz.

20. Serial Programming Algorithm

To program and verify the AT89S52 in the serial programming mode, the following sequence is recommended:

1. Power-up sequence:
 - a. Apply power between VCC and GND pins.
 - b. Set RST pin to “H”.

If a crystal is not connected across pins XTAL1 and XTAL2, apply a 3 MHz to 33 MHz clock to XTAL1 pin and wait for at least 10 milliseconds.

2. Enable serial programming by sending the Programming Enable serial instruction to pin MOSI/P1.5. The frequency of the shift clock supplied at pin SCK/P1.7 needs to be less than the CPU clock at XTAL1 divided by 16.
3. The Code array is programmed one byte at a time in either the Byte or Page mode. The write cycle is self-timed and typically takes less than 0.5 ms at 5V.
4. Any memory location can be verified by using the Read instruction which returns the content at the selected address at serial output MISO/P1.6.
5. At the end of a programming session, RST can be set low to commence normal device operation.

Power-off sequence (if needed):

1. Set XTAL1 to “L” (if a crystal is not used).
2. Set RST to “L”.
3. Turn V_{CC} power off.

Data Polling: The $\overline{\text{Data}}$ Polling feature is also available in the serial mode. In this mode, during a write cycle an attempted read of the last byte written will result in the complement of the MSB of the serial output byte on MISO.

21. Serial Programming Instruction Set






The Instruction Set for Serial Programming follows a 4-byte protocol and is shown in Table 24-1.

22. Programming Interface – Parallel Mode

Every code byte in the Flash array can be programmed by using the appropriate combination of control signals. The write operation cycle is self-timed and once initiated, will automatically time itself to completion.

Most major worldwide programming vendors offer support for the Atmel AT89 microcontroller series. Please contact your local programming vendor for the appropriate software revision.

Table 22-1. Flash Programming Modes

Mode	V _{CC}	RST	$\overline{\text{PSEN}}$	$\overline{\text{ALE/PROG}}$	$\overline{\text{EA/V}}_{\text{PP}}$	P2.6	P2.7	P3.3	P3.6	P3.7	P0.7-0 Data	P2.4-0	P1.7-0
												Address	
Write Code Data	5V	H	L		12V	L	H	H	H	H	D _{IN}	A12-8	A7-0
Read Code Data	5V	H	L	H	H	L	L	L	H	H	D _{OUT}	A12-8	A7-0
Write Lock Bit 1	5V	H	L		12V	H	H	H	H	H	X	X	X
Write Lock Bit 2	5V	H	L		12V	H	H	H	L	L	X	X	X
Write Lock Bit 3	5V	H	L		12V	H	L	H	H	L	X	X	X
Read Lock Bits 1, 2, 3	5V	H	L	H	H	H	H	L	H	L	P0.2, P0.3, P0.4	X	X
Chip Erase	5V	H	L		12V	H	L	H	L	L	X	X	X
Read Atmel ID	5V	H	L	H	H	L	L	L	L	L	1EH	X 0000	00H
Read Device ID	5V	H	L	H	H	L	L	L	L	L	52H	X 0001	00H
Read Device ID	5V	H	L	H	H	L	L	L	L	L	06H	X 0010	00H

- Notes:
1. Each $\overline{\text{PROG}}$ pulse is 200 ns - 500 ns for Chip Erase.
 2. Each $\overline{\text{PROG}}$ pulse is 200 ns - 500 ns for Write Code Data.
 3. Each $\overline{\text{PROG}}$ pulse is 200 ns - 500 ns for Write Lock Bits.
 4. RDY/BSY signal is output on P3.0 during programming.
 5. X = don't care.

Figure 22-1. Programming the Flash Memory (Parallel Mode)

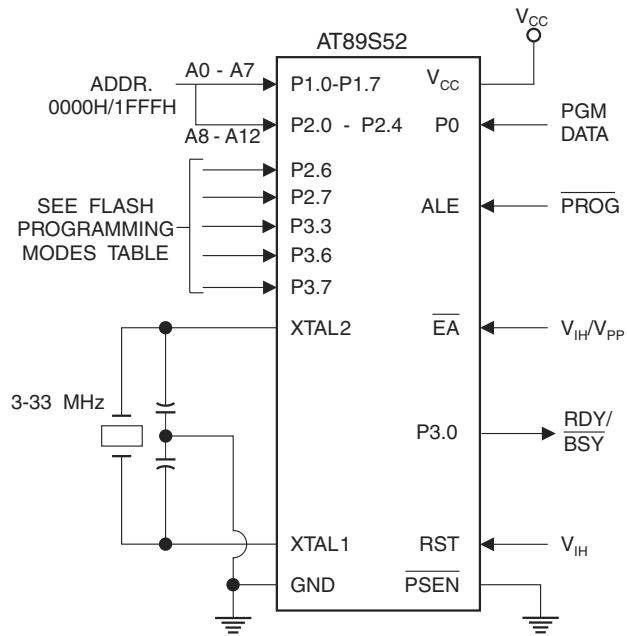
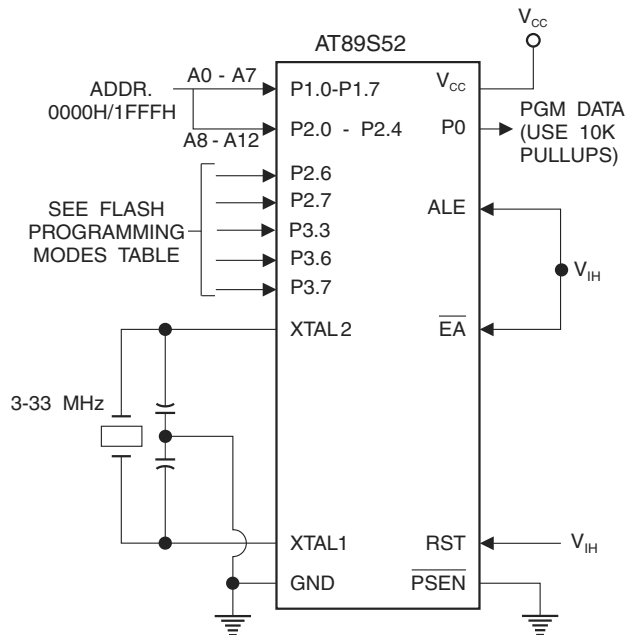


Figure 22-2. Verifying the Flash Memory (Parallel Mode)



23. Flash Programming and Verification Characteristics (Parallel Mode)

$T_A = 20^\circ\text{C}$ to 30°C , $V_{CC} = 4.5$ to 5.5V

Symbol	Parameter	Min	Max	Units
V_{PP}	Programming Supply Voltage	11.5	12.5	V
I_{PP}	Programming Supply Current		10	mA
I_{CC}	V_{CC} Supply Current		30	mA
$1/t_{CLCL}$	Oscillator Frequency	3	33	MHz
t_{AVGL}	Address Setup to \overline{PROG} Low	$48 t_{CLCL}$		
t_{GHAX}	Address Hold After \overline{PROG}	$48 t_{CLCL}$		
t_{DVGL}	Data Setup to \overline{PROG} Low	$48 t_{CLCL}$		
t_{GHDX}	Data Hold After \overline{PROG}	$48 t_{CLCL}$		
t_{EHS}	P2.7 (\overline{ENABLE}) High to V_{PP}	$48 t_{CLCL}$		
t_{SHGL}	V_{PP} Setup to \overline{PROG} Low	10		μs
t_{GHSL}	V_{PP} Hold After \overline{PROG}	10		μs
t_{GLGH}	\overline{PROG} Width	0.2	1	μs
t_{AVQV}	Address to Data Valid		$48 t_{CLCL}$	
t_{ELQV}	\overline{ENABLE} Low to Data Valid		$48 t_{CLCL}$	
t_{EHQZ}	Data Float After \overline{ENABLE}	0	$48 t_{CLCL}$	
t_{GHBL}	\overline{PROG} High to \overline{BUSY} Low		1.0	μs
t_{WC}	Byte Write Cycle Time		50	μs

Figure 23-1. Flash Programming and Verification Waveforms – Parallel Mode

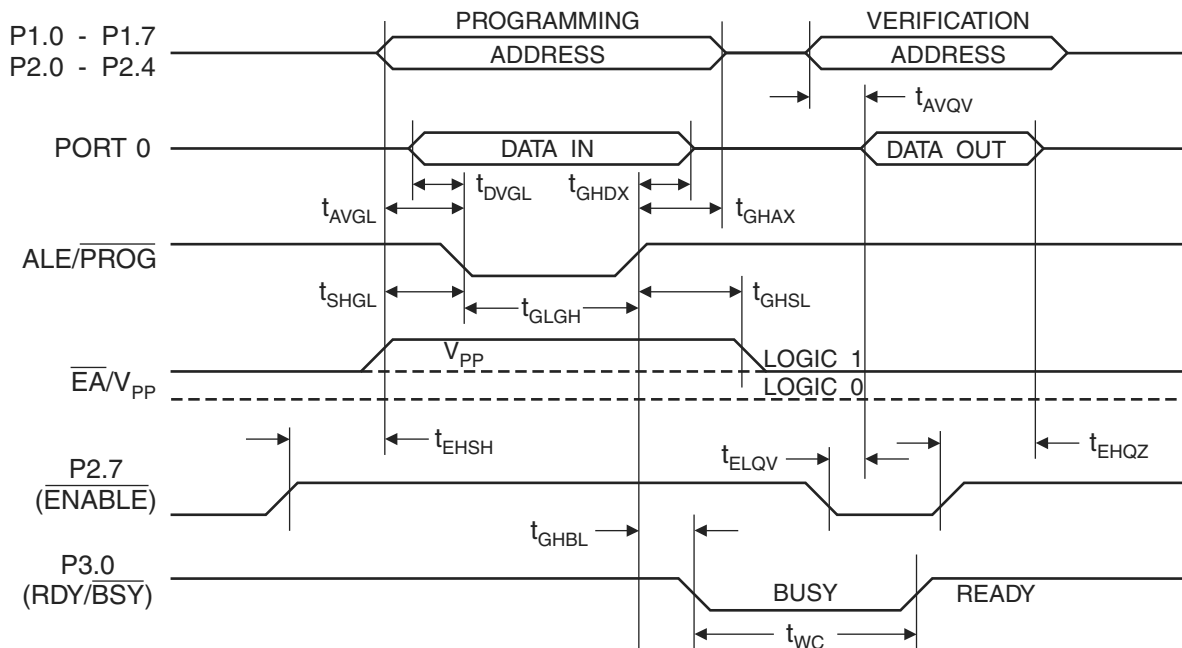
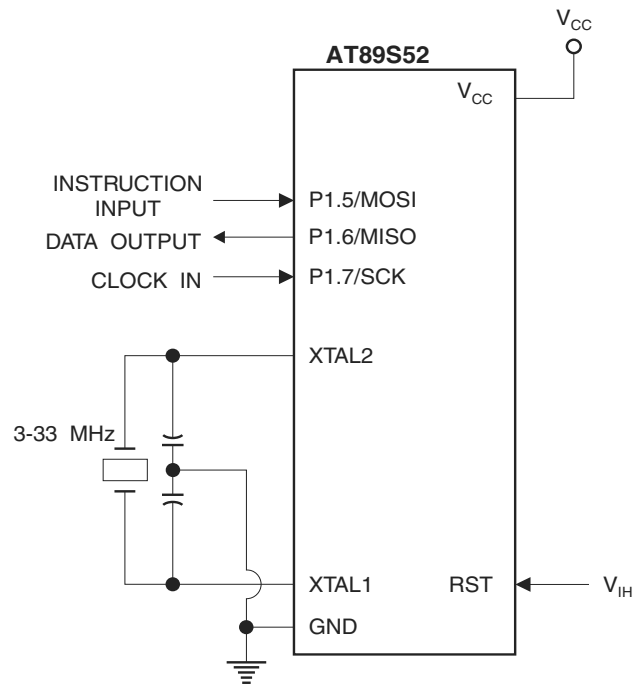


Figure 23-2. Flash Memory Serial Downloading



24. Flash Programming and Verification Waveforms – Serial Mode

Figure 24-1. Serial Programming Waveforms

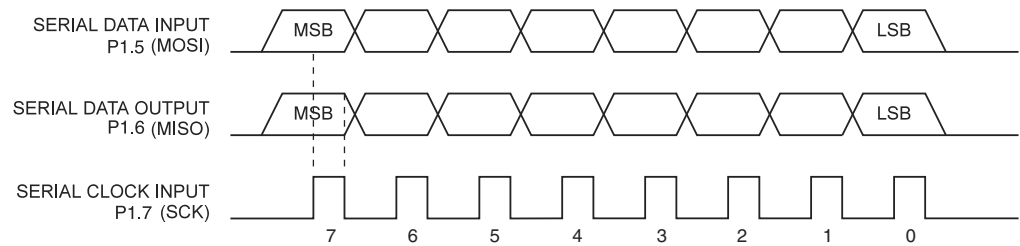


Table 24-1. Serial Programming Instruction Set

Instruction	Instruction Format	Byte 2	Byte 3	Byte 4	Operation
	Byte 1				
Programming Enable	1010 1100	0101 0011	xxxx xxxx	xxxx xxxx 0110 1001 (Output on MISO)	Enable Serial Programming while RST is high
Chip Erase	1010 1100	100x xxxx	xxxx xxxx	xxxx xxxx	Chip Erase Flash memory array
Read Program Memory (Byte Mode)	0010 0000	xxx A12 A11 A10 A9 A8	A7 A6 A5 A4 A3 A2 A1 A0	D0 D1 D2 D3 D4 D5 D6 D7	Read data from Program memory in the byte mode
Write Program Memory (Byte Mode)	0100 0000	xxx A12 A11 A10 A9 A8	A7 A6 A5 A4 A3 A2 A1 A0	D0 D1 D2 D3 D4 D5 D6 D7	Write data to Program memory in the byte mode
Write Lock Bits ⁽¹⁾	1010 1100	1110 0011 B3 B2 B1 B0	xxxx xxxx	xxxx xxxx	Write Lock bits. See Note (1).
Read Lock Bits	0010 0100	xxxx xxxx	xxxx xxxx	xxx B3 B2 B1 B0 xx	Read back current status of the lock bits (a programmed lock bit reads back as a "1")
Read Signature Bytes	0010 1000	xxx A12 A11 A10 A9 A8	A7 xxx xxx0	Signature Byte	Read Signature Byte
Read Program Memory (Page Mode)	0011 0000	xxx A12 A11 A10 A9 A8	Byte 0	Byte 1... Byte 255	Read data from Program memory in the Page Mode (256 bytes)
Write Program Memory (Page Mode)	0101 0000	xxx A12 A11 A10 A9 A8	Byte 0	Byte 1... Byte 255	Write data to Program memory in the Page Mode (256 bytes)

Note: 1. B1 = 0, B2 = 0 ---> Mode 1, no lock protection
 B1 = 0, B2 = 1 ---> Mode 2, lock bit 1 activated
 B1 = 1, B2 = 0 ---> Mode 3, lock bit 2 activated
 B1 = 1, B2 = 1 ---> Mode 4, lock bit 3 activated

Each of the lock bit modes needs to be activated sequentially before Mode 4 can be executed.

After Reset signal is high, SCK should be low for at least 64 system clocks before it goes high to clock in the enable data bytes. No pulsing of Reset signal is necessary. SCK should be no faster than 1/16 of the system clock at XTAL1.

For Page Read/Write, the data always starts from byte 0 to 255. After the command byte and upper address byte are latched, each byte thereafter is treated as data until all 256 bytes are shifted in/out. Then the next instruction will be ready to be decoded.

25. Serial Programming Characteristics

Figure 25-1. Serial Programming Timing

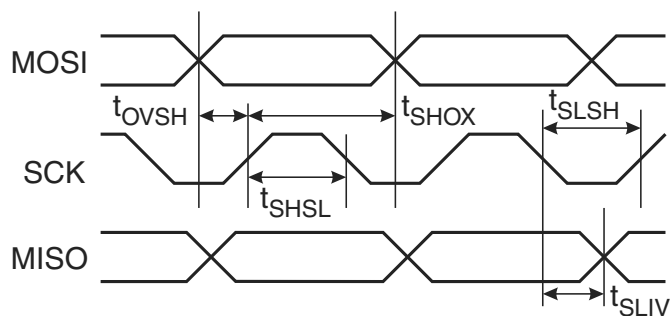


Table 25-1. Serial Programming Characteristics, $T_A = -40^\circ\text{C}$ to 85°C , $V_{CC} = 4.0 - 5.5\text{V}$ (Unless Otherwise Noted)

Symbol	Parameter	Min	Typ	Max	Units
$1/t_{CLCL}$	Oscillator Frequency	3		33	MHz
t_{CLCL}	Oscillator Period	30			ns
t_{SHSL}	SCK Pulse Width High	$8 t_{CLCL}$			ns
t_{SLSH}	SCK Pulse Width Low	$8 t_{CLCL}$			ns
t_{OVSH}	MOSI Setup to SCK High	t_{CLCL}			ns
t_{SHOX}	MOSI Hold after SCK High	$2 t_{CLCL}$			ns
t_{SLIV}	SCK Low to MISO Valid	10	16	32	ns
t_{ERASE}	Chip Erase Instruction Cycle Time			500	ms
t_{SWC}	Serial Byte Write Cycle Time			$64 t_{CLCL} + 400$	μs

28. AC Characteristics

Under operating conditions, load capacitance for Port 0, ALE/ $\overline{\text{PROG}}$, and $\overline{\text{PSEN}}$ = 100 pF; load capacitance for all other outputs = 80 pF.

28.1 External Program and Data Memory Characteristics

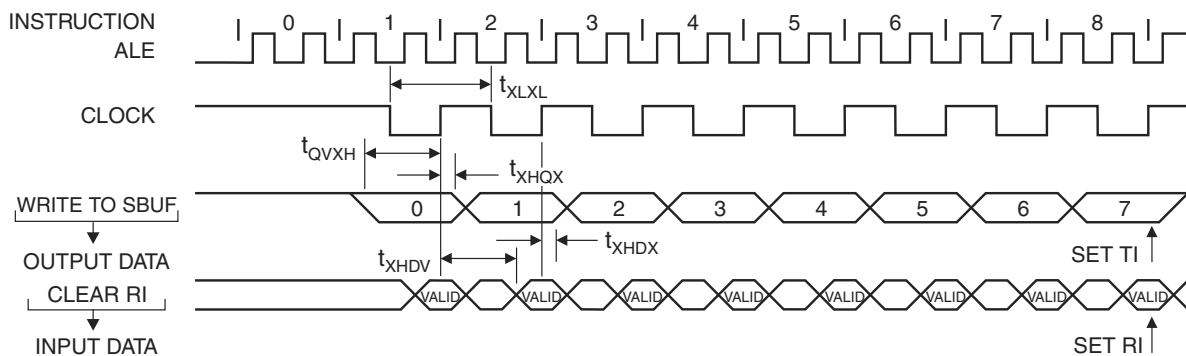
Symbol	Parameter	12 MHz Oscillator		Variable Oscillator		Units
		Min	Max	Min	Max	
$1/t_{\text{CLCL}}$	Oscillator Frequency			0	33	MHz
t_{LHLL}	ALE Pulse Width	127		$2t_{\text{CLCL}}-40$		ns
t_{AVLL}	Address Valid to ALE Low	43		$t_{\text{CLCL}}-25$		ns
t_{LLAX}	Address Hold After ALE Low	48		$t_{\text{CLCL}}-25$		ns
t_{LLIV}	ALE Low to Valid Instruction In		233		$4t_{\text{CLCL}}-65$	ns
t_{LLPL}	ALE Low to $\overline{\text{PSEN}}$ Low	43		$t_{\text{CLCL}}-25$		ns
t_{PLPH}	$\overline{\text{PSEN}}$ Pulse Width	205		$3t_{\text{CLCL}}-45$		ns
t_{PLIV}	$\overline{\text{PSEN}}$ Low to Valid Instruction In		145		$3t_{\text{CLCL}}-60$	ns
t_{PXIX}	Input Instruction Hold After $\overline{\text{PSEN}}$	0		0		ns
t_{PXIZ}	Input Instruction Float After $\overline{\text{PSEN}}$		59		$t_{\text{CLCL}}-25$	ns
t_{PXAV}	$\overline{\text{PSEN}}$ to Address Valid	75		$t_{\text{CLCL}}-8$		ns
t_{AVIV}	Address to Valid Instruction In		312		$5t_{\text{CLCL}}-80$	ns
t_{PLAZ}	$\overline{\text{PSEN}}$ Low to Address Float		10		10	ns
t_{RLRH}	$\overline{\text{RD}}$ Pulse Width	400		$6t_{\text{CLCL}}-100$		ns
t_{WLWH}	$\overline{\text{WR}}$ Pulse Width	400		$6t_{\text{CLCL}}-100$		ns
t_{RLDV}	$\overline{\text{RD}}$ Low to Valid Data In		252		$5t_{\text{CLCL}}-90$	ns
t_{RHDX}	Data Hold After $\overline{\text{RD}}$	0		0		ns
t_{RHDZ}	Data Float After $\overline{\text{RD}}$		97		$2t_{\text{CLCL}}-28$	ns
t_{LLDV}	ALE Low to Valid Data In		517		$8t_{\text{CLCL}}-150$	ns
t_{AVDV}	Address to Valid Data In		585		$9t_{\text{CLCL}}-165$	ns
t_{LLWL}	ALE Low to $\overline{\text{RD}}$ or $\overline{\text{WR}}$ Low	200	300	$3t_{\text{CLCL}}-50$	$3t_{\text{CLCL}}+50$	ns
t_{AVWL}	Address to $\overline{\text{RD}}$ or $\overline{\text{WR}}$ Low	203		$4t_{\text{CLCL}}-75$		ns
t_{QVWX}	Data Valid to $\overline{\text{WR}}$ Transition	23		$t_{\text{CLCL}}-30$		ns
t_{QVWH}	Data Valid to $\overline{\text{WR}}$ High	433		$7t_{\text{CLCL}}-130$		ns
t_{WHQX}	Data Hold After $\overline{\text{WR}}$	33		$t_{\text{CLCL}}-25$		ns
t_{RLAZ}	$\overline{\text{RD}}$ Low to Address Float		0		0	ns
t_{WHLH}	$\overline{\text{RD}}$ or $\overline{\text{WR}}$ High to ALE High	43	123	$t_{\text{CLCL}}-25$	$t_{\text{CLCL}}+25$	ns

34. Serial Port Timing: Shift Register Mode Test Conditions

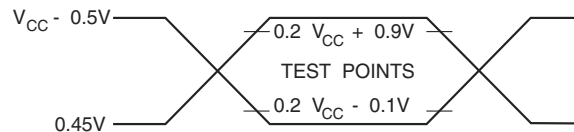
The values in this table are valid for $V_{CC} = 4.0V$ to $5.5V$ and Load Capacitance = 80 pF .

Symbol	Parameter	12 MHz Osc		Variable Oscillator		Units
		Min	Max	Min	Max	
t_{XLXL}	Serial Port Clock Cycle Time	1.0		$12 t_{CLCL}$		μs
t_{QVXH}	Output Data Setup to Clock Rising Edge	700		$10 t_{CLCL} - 133$		ns
t_{XHGX}	Output Data Hold After Clock Rising Edge	50		$2 t_{CLCL} - 80$		ns
t_{XHDX}	Input Data Hold After Clock Rising Edge	0		0		ns
t_{XHDV}	Clock Rising Edge to Input Data Valid		700		$10 t_{CLCL} - 133$	ns

35. Shift Register Mode Timing Waveforms

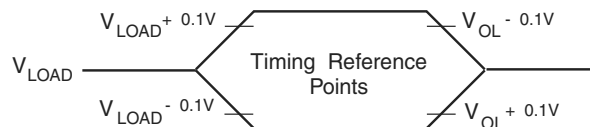


36. AC Testing Input/Output Waveforms⁽¹⁾



Note: 1. AC Inputs during testing are driven at $V_{CC} - 0.5V$ for a logic 1 and $0.45V$ for a logic 0. Timing measurements are made at V_{IH} min. for a logic 1 and V_{IL} max. for a logic 0.

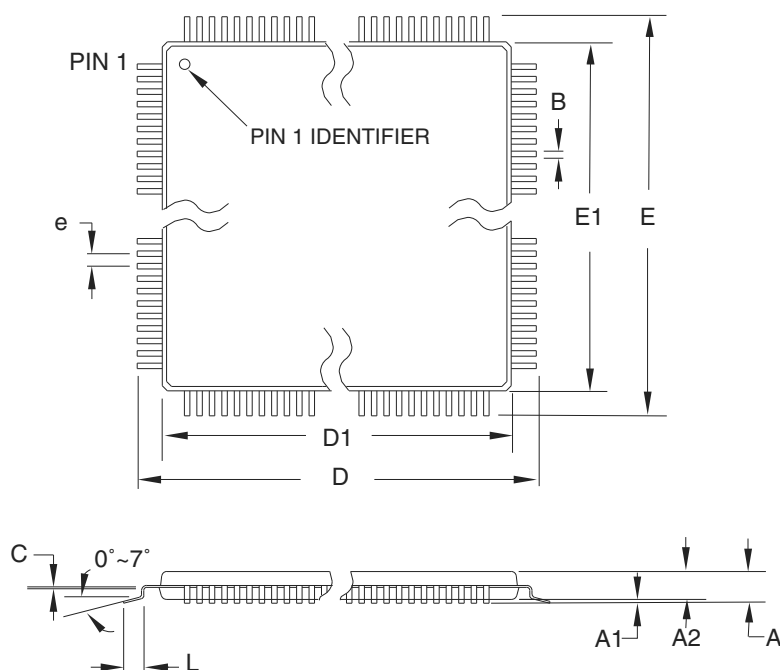
37. Float Waveforms⁽¹⁾



Note: 1. For timing purposes, a port pin is no longer floating when a 100 mV change from load voltage occurs. A port pin begins to float when a 100 mV change from the loaded V_{OH}/V_{OL} level occurs.

39. Packaging Information

39.1 44A – TQFP



COMMON DIMENSIONS
(Unit of Measure = mm)

SYMBOL	MIN	NOM	MAX	NOTE
A	—	—	1.20	
A1	0.05	—	0.15	
A2	0.95	1.00	1.05	
D	11.75	12.00	12.25	
D1	9.90	10.00	10.10	Note 2
E	11.75	12.00	12.25	
E1	9.90	10.00	10.10	Note 2
B	0.30	—	0.45	
C	0.09	—	0.20	
L	0.45	—	0.75	
e	0.80 TYP			

- Notes:
1. This package conforms to JEDEC reference MS-026, Variation ACB.
 2. Dimensions D1 and E1 do not include mold protrusion. Allowable protrusion is 0.25 mm per side. Dimensions D1 and E1 are maximum plastic body size dimensions including mold mismatch.
 3. Lead coplanarity is 0.10 mm maximum.

10/5/2001

2325 Orchard Parkway San Jose, CA 95131	TITLE	DRAWING NO.	REV.
	44A , 44-lead, 10 x 10 mm Body Size, 1.0 mm Body Thickness, 0.8 mm Lead Pitch, Thin Profile Plastic Quad Flat Package (TQFP)	44A	B